



NEO 3400

Mass
production

Resist strip /
descum

High dose
implant strip

Etching



When plasma matters



NEO 3400



The NEO 3400 series production platform is one of the latest additions to the industry leading NEO range of advanced plasma ashing and etching products from Trymax Semiconductor Equipment.

It's ready for the highest volume of production and adaptable to every production ramp and budget. The NEO 3400 platform can be configured with any of the available Trymax NEO process modules and is compatible with substrates up to 300mm in diameter. The small footprint and modular design can be flexibly configured based on your production needs.

This platform can be used as a full bridge tool with compatibility to run both 200 and 300mm diameter substrates.

Features

- 200/300mm substrate size
- 4 loadports
- 4 axis dual arm robot handling with x-track
- 2 or 4 process chambers
- 3 different process chamber technologies available:
 - Microwave downstream (2.45 GHz)
 - RF bias (13.56 MHz)
 - Dual Source (Microwave, RF bias)
- Mechanical throughput >300wph
- Compact footprint
- Very low Cost of Ownership
- Fully digital controlled, devicenet-ethernet
- Windows based industrial computers

Applications

- Bulk resist, post LDI resist strip
- Descum processing
- Polymer removal
- Post high dose implant strip
- Silicon nitride/silicon carbide etch applications
- TaSi etch
- MEMS applications
- Advanced packaging processing (PR, PI, BCB, PBO)
- RF filter BAW/SAW resist processing

Compliance

- SEMI S2-01
- SEMI S8-01
- CE EU-RoHs
- UL (optional)



Contact us now

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